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Triple Inverter with Open Drain Outputs

NL37WZ06

The NL37WZ06 is a high performance triple inverter with open drain outputs operating from a 1.65 V to 5.5 V supply.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.1 ns t_{PD} at V_{CC} = 5 V (Typ)
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in US8, UDFN8 and UQFN8 Packages
- Chip Complexity < 100 FETs
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant
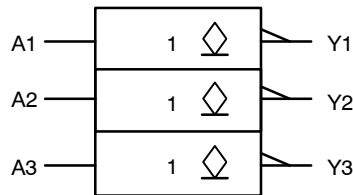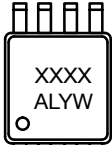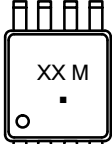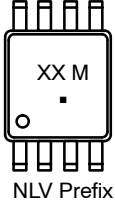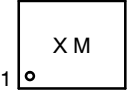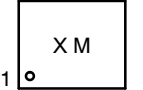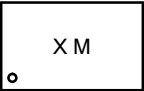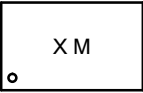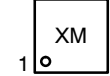
Figure 1. Logic Symbol

ON Semiconductor®

MARKING DIAGRAMS

US8
US SUFFIX
CASE 493

XXXX
ALYW

Commercial

XX M
.

NLV Prefix

UDFN8, 1.45x1.0
MU3 SUFFIX
CASE 517BZ

X M
1

UDFN8, 1.95x1.0
MU1 SUFFIX
CASE 517CA

X M
1

UQFN8, 1.4x1.2
MQ2 SUFFIX
CASE 523AS

XM
1

UQFN8, 1.6x1.6
MQ1 SUFFIX
CASE 523AN

1
XX M■

X, XX, XXXX	= Specific Device Code
A	= Assembly Location
L	= Lot Code
Y	= Year Code
W	= Week Code
M	= Date Code
■	= Pb−Free Package

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NL37WZ06

US8

UDFN8

UQFN8 (Top View)
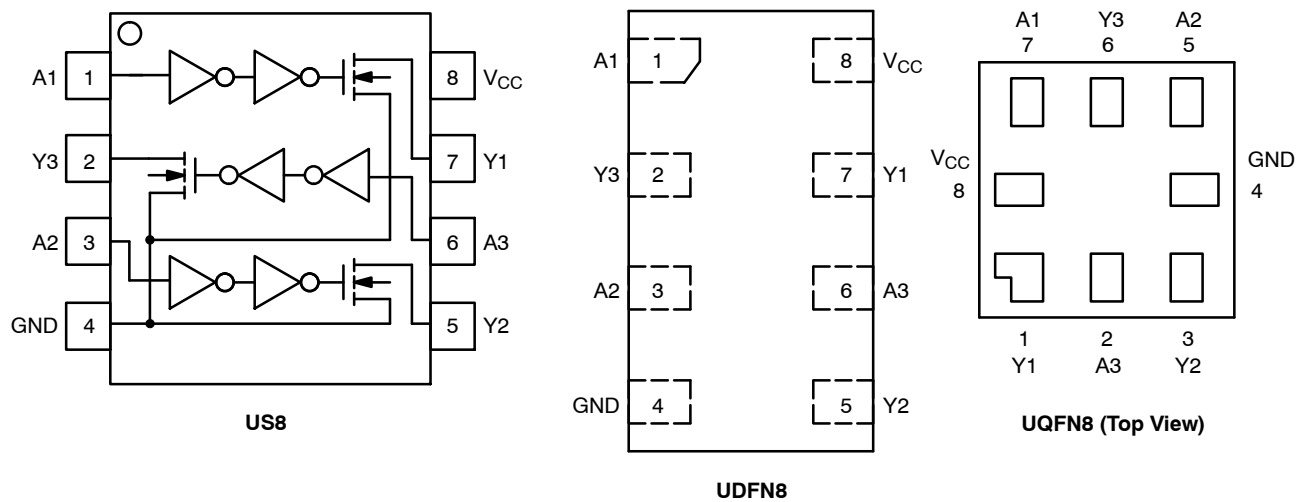
Figure 2. Pinout

PIN ASSIGNMENT

Pin	US8 / UDFN8	UQFN8
1	A1	Y1
2	Y3	A3
3	A2	Y2
4	GND	GND
5	Y2	A2
6	A3	Y3
7	Y1	A1
8	V_{CC}	V_{CC}

FUNCTION TABLE

A Input	Y Output
L	Z
H	L

NL37WZ06

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +6.5	V
V_{IN}	DC Input Voltage		−0.5 to +6.5	V
V_{OUT}	DC Output Voltage	Active−Mode (High or Low State) Tri−State Mode (Note 1) Power−Down Mode (V_{CC} = 0 V)	−0.5 to V_{CC} + 0.5 −0.5 to +6.5 −0.5 to +6.5	V
I_{IK}	DC Input Diode Current	V_{IN} < GND	−50	mA
I_{OK}	DC Output Diode Current	V_{OUT} < GND	−50	mA
I_{OUT}	DC Output Source/Sink Current		±50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 secs		260	°C
T_J	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance (Note 2)	US8 UQFN8 UDFN8	250 210 231	°C/W
P_D	Power Dissipation in Still Air	US8 UQFN8 UDFN8	500 595 541	mW
MSL	Moisture Sensitivity		Level 1	–
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	–
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
$I_{Latchup}$	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Applicable to devices with outputs that may be tri−stated.
2. Measured with minimum pad spacing on an FR4 board, using 10mm−by−1inch, 2 ounce copper trace no air flow per JESD51−7.
3. HBM tested to ANSI/ESDA/JEDEC JS−001−2017. CDM tested to EIA/JESD22−C101−F. JEDEC recommends that ESD qualification to EIA/JESD22−A115−A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics		Min	Max	Unit
V_{CC}	Positive DC Supply Voltage		1.65	5.5	V
V_{IN}	DC Input Voltage		0	5.5	V
V_{OUT}	DC Output Voltage	Active−Mode (High or Low State) Tri−State Mode (Note 1) Power−Down Mode (V_{CC} = 0 V)	0 0 0	V_{CC} 5.5 5.5	
T_A	Operating Temperature Range		−55	+125	°C
t_r , t_f	Input Rise and Fall Time	V_{CC} = 1.65 V to 1.95 V V_{CC} = 2.3 V to 2.7 V V_{CC} = 3.0 V to 3.6 V V_{CC} = 4.5 V to 5.5 V	0 0 0 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	$T_A = 25°C$			$-55°C \leq T_A \leq 125°C$		Units
				Min	Typ	Max	Min	Max	
V_{IH}	High–Level Input Voltage		1.65 to 1.95	0.65 V_{CC}	–	–	0.65 V_{CC}	–	V
			2.3 to 5.5	0.70 V_{CC}	–	–	0.70 V_{CC}	–	
V_{IL}	Low–Level Input Voltage		1.65 to 1.95	–	–	0.35 V_{CC}	–	0.35 V_{CC}	V
			2.3 to 5.5	–	–	0.30 V_{CC}	–	0.30 V_{CC}	
V_{OL}	Low–Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 100$ μA $I_{OL} = 4$ mA $I_{OL} = 8$ mA $I_{OL} = 12$ mA $I_{OL} = 16$ mA $I_{OL} = 24$ mA $I_{OL} = 32$ mA	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	– – – – – – –	– 0.08 0.2 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55	– – – – – – –	0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I_{IN}	Input Leakage Current	$V_{IN} = 5.5$ V or GND	1.65 to 5.5	–	–	±0.1	–	±1.0	μA
I_{OFF}	Power Off Leakage Current	$V_{IN} = 5.5$ V or $V_{OUT} = 5.5$ V	0	–	–	1.0	–	10	μA
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	–	–	1.0	–	10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	$T_A = 25°C$			$-55°C \leq T_A \leq 125°C$		Units
				Min	Typ	Max	Min	Max	
t_{PZL}	Propagation Delay, A to Y (Figures 3 and 4)		1.65 to 1.95	–	6.0	9.0	–	9.5	ns
			2.3 to 2.7	–	3.6	6.1	–	6.5	
			3.0 to 3.6	–	2.7	5.6	–	6.0	
			4.5 to 5.5	–	2.1	4.4	–	4.8	
t_{PLZ}	Propagation Delay, A to Y (Figures 3 and 4)		1.65 to 1.95	–	4.0	9.0	–	9.5	ns
			2.3 to 2.7	–	2.8	6.1	–	6.5	
			3.0 to 3.6	–	2.5	5.6	–	6.0	
			4.5 to 5.5		2.2	4.4	–	4.8	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C_{IN}	Input Capacitance	$V_{CC} = 5.5$ V, $V_{IN} = 0$ V or V_{CC}	2.5	pF
C_{OUT}	Output Capacitance	$V_{CC} = 5.5$ V, $V_{IN} = 0$ V or V_{CC}	2.5	pF
C_{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, $V_{CC} = 3.3$ V, $V_{IN} = 0$ V or V_{CC} 10 MHz, $V_{CC} = 5.5$ V, $V_{IN} = 0$ V or V_{CC}	9 11	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

NL37WZ06
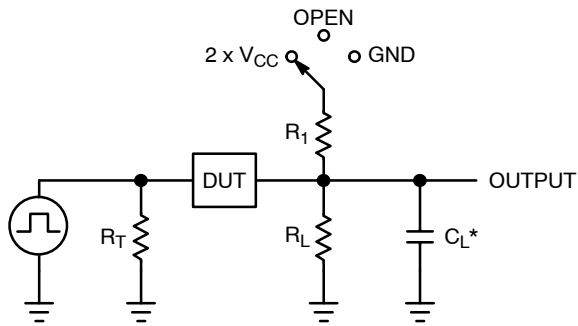
C_L includes probe and jig capacitance
R_T is Z_{OUT} of pulse generator (typically 50 Ω)
f = 1 MHz

Figure 3. Test Circuit

Test	Switch Position	C_L, pF	R_L, Ω	R_1, Ω
t_{PLH} / t_{PHL}	Open	See AC Characteristics Table		
t_{PLZ} / t_{PZL}	2 x V_CC	50	500	500
t_{PHZ} / t_{PZH}	GND	50	500	500

X = Don't Care

Figure 4. Switching Waveforms

V_CC, V	V_mi, V	V_mo, V		V_Y, V
		t_{PLH}, t_{PHL}	t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}	
1.65 to 1.95	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
2.3 to 2.7	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
3.0 to 3.6	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3
4.5 to 5.5	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3

NL37WZ06

DEVICE ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping†
NL37WZ06USG	US8	LF	Q4	3000 / Tape & Reel
NL37WZ06MQ1TCG (In Development)	UQFN8, 1.6 x 1.6, 0.5P	TBD	TBD	3000 / Tape & Reel
NL37WZ06MU1TCG (In Development)	UDFN8, 1.95 x 1.0, 0.5P	TBD	TBD	3000 / Tape & Reel
NL37WZ06MU3TCG (In Development)	UDFN8, 1.45 x 1.0, 0.35P	TBD	TBD	3000 / Tape & Reel
NL37WZ06MQ2TCG (In Development)	UQFN8, 1.4 x 1.2, 0.4P	TBD	TBD	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable.
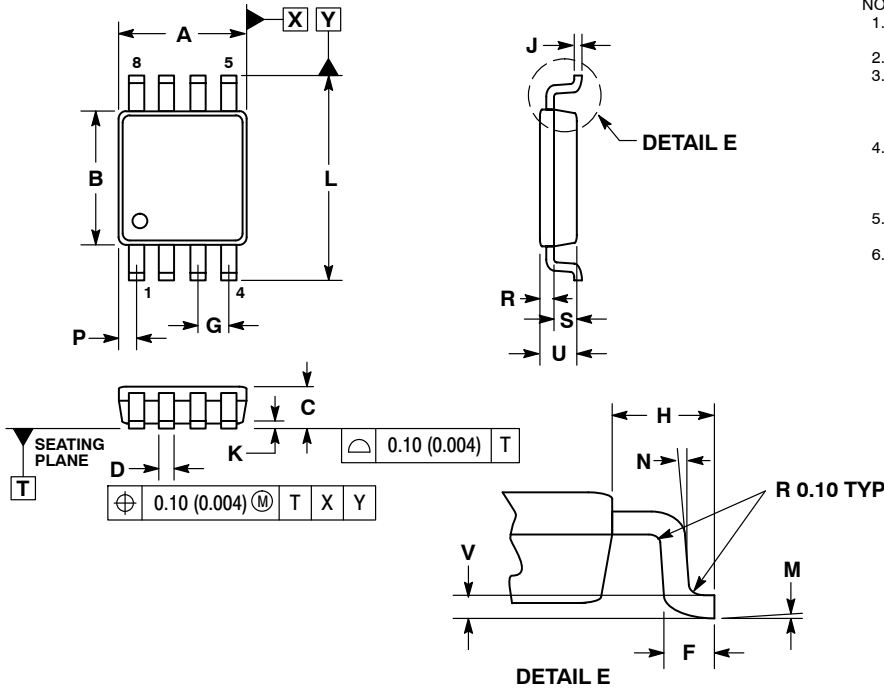
Pin 1 Orientation in Tape and Reel
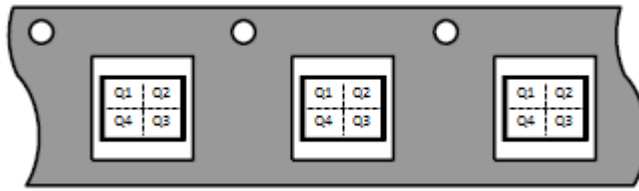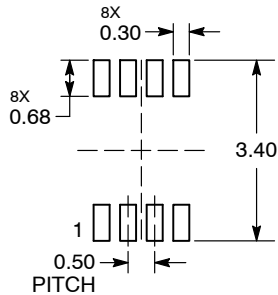
PACKAGE DIMENSIONS

US8
CASE 493
ISSUE D

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR. MOLD FLASH. PROTRUSION AND GATE BURR SHALL NOT EXCEED 0.14MM (0.0055") PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.14MM (0.0055") PER SIDE.
5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076–0.0203MM (0.003–0.008").
6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.0508MM (0.0002").

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.90	2.10	0.075	0.083
B	2.20	2.40	0.087	0.094
C	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50 BSC		0.020 BSC	
H	0.40 REF		0.016 REF	
J	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.20	0.118	0.128
M	0 °	6 °	0 °	6 °
N	0 °	10 °	0 °	10 °
P	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V	0.12 BSC		0.005 BSC	

DETAIL E

SEATING PLANE

0.10 (0.004) T

⊕ 0.10 (0.004) Ⓜ T X Y

R 0.10 TYP

DETAIL E

RECOMMENDED SOLDERING FOOTPRINT*

8X
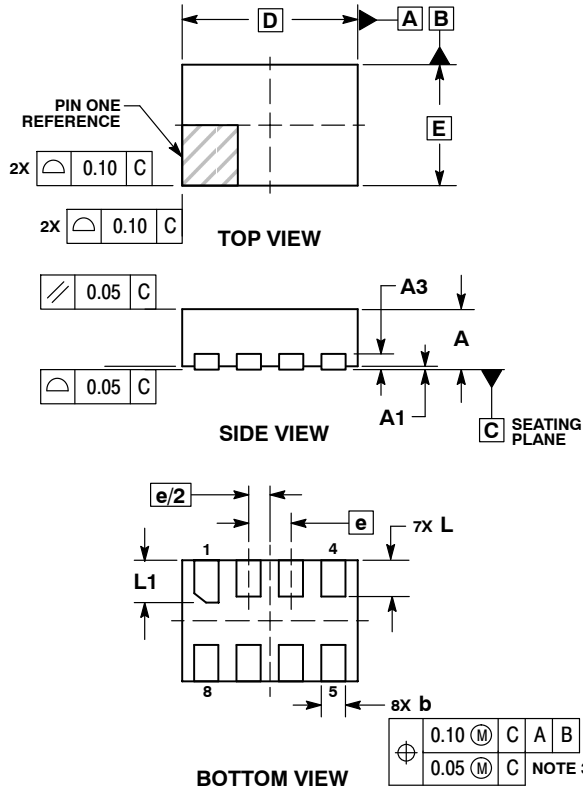0.30

8X
0.68

3.40

1

0.50
PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN8, 1.45x1, 0.35P
CASE 517BZ−01
ISSUE O

TOP VIEW

2X ⌒ 0.10 C

2X ⌒ 0.10 C

PIN ONE
REFERENCE

D

A B

E

SIDE VIEW

⫽ 0.05 C

⌒ 0.05 C

A3

A

A1

C SEATING PLANE

BOTTOM VIEW

e/2

e

7X L

L1

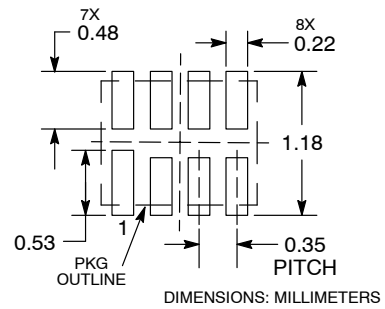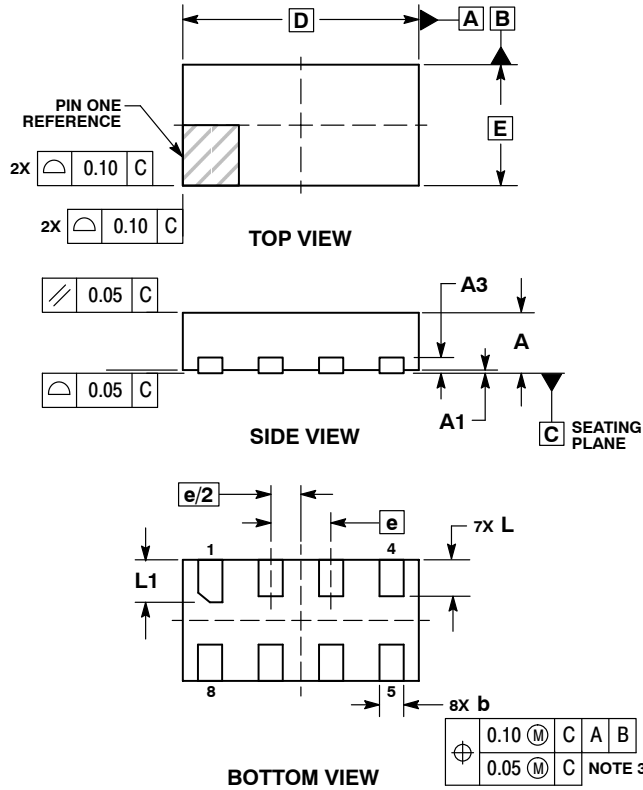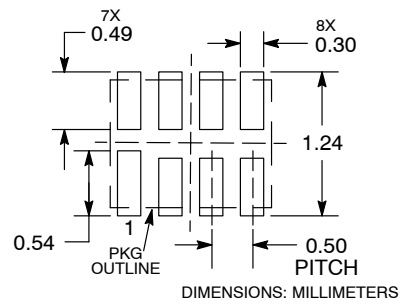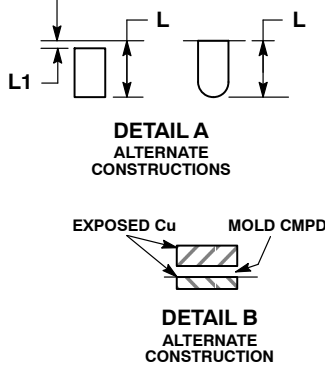1   4

8   5

8X b

⊕ | 0.10 Ⓜ | C | A | B
0.05 Ⓜ | C | NOTE 3

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*

7X
0.48

8X
0.22

1.18

0.53

1

0.35
PITCH

PKG
OUTLINE

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.
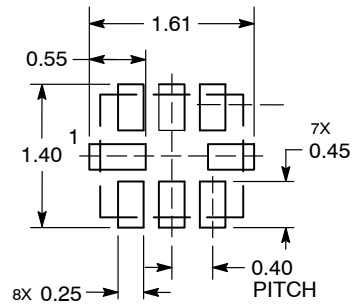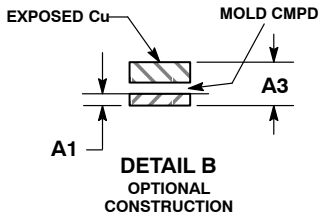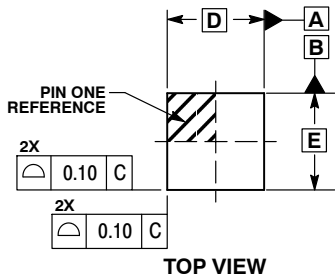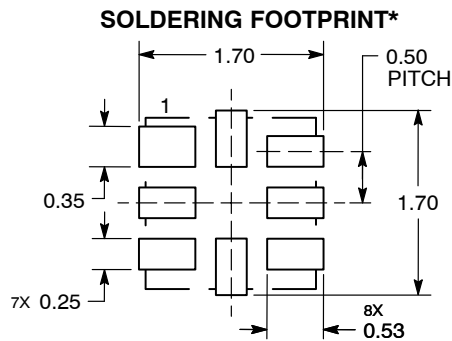
NL37WZ06

PACKAGE DIMENSIONS

UDFN8, 1.95x1, 0.5P
CASE 517CA–01
ISSUE O

PIN ONE REFERENCE

2X | 0.10 | C

2X | 0.10 | C

TOP VIEW

0.05 | C

SIDE VIEW

A3

A

A1

C | **SEATING PLANE**

e/2

e

7X L

1   4

L1

8   5

8X **b**

BOTTOM VIEW

| ⊕ | 0.10 Ⓜ | C | A | B |
| | 0.05 Ⓜ | C | **NOTE 3** |

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

| DIM | MILLIMETERS | |
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.95 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*

7X
0.49

8X
0.30

1.24

0.54

1

PKG OUTLINE

0.50 PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.
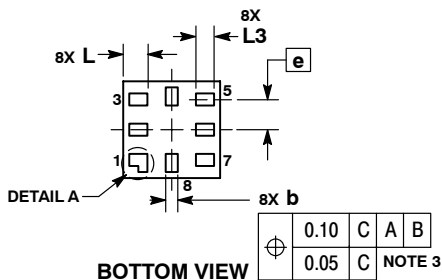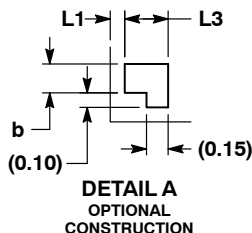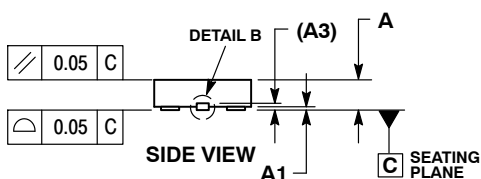
NL37WZ06

PACKAGE DIMENSIONS

UQFN8, 1.4x1.2, 0.4P
CASE 523AS
ISSUE A
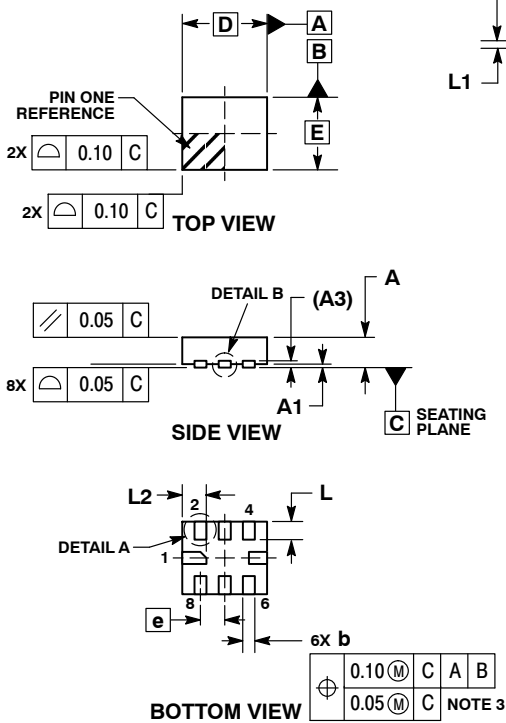
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25 mm FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.40 BSC	
E	1.20 BSC	
e	0.40 BSC	
L	0.20	0.40
L1	---	0.15
L2	0.30	0.50

TOP VIEW

DETAIL A
ALTERNATE CONSTRUCTIONS

SIDE VIEW

DETAIL B
ALTERNATE CONSTRUCTION

BOTTOM VIEW

SOLDERING FOOTPRINT*

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UQFN8, 1.6x1.6, 0.5P
CASE 523AN–01
ISSUE O

TOP VIEW

SIDE VIEW

DETAIL B
OPTIONAL
CONSTRUCTION

DETAIL A
OPTIONAL
CONSTRUCTION

BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.60 BSC	
E	1.60 BSC	
e	0.50 BSC	
L	0.35	0.45
L1	–––	0.15
L3	0.25	0.35

SOLDERING FOOTPRINT*

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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